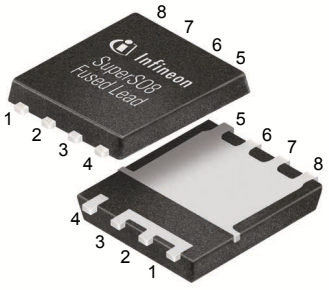
MOSFET

OptiMOS™ 5 Linear FET 2, 60 V

TDSON-8 FL (enlarged source interconnection)



Features

- Ideal for hot-swap, battery protection and e-fuse applications
- Very low on-resistance $R_{DS(on)}$
- Wide safe operating area SOA
- N-channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Fully qualified according to JEDEC for Industrial Applications

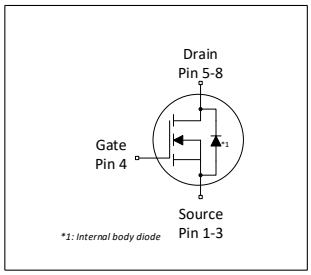


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	60	V
$R_{DS(on),max}$	1.55	mΩ
I_D	275	A
$I(V_{DS}=30\ V, t_p=10\ ms)$	8.3	A

Type / Ordering Code	Package	Marking	Related Links
ISC015N06NM5LF2	PG-TDSON-8 FL	15N06LF2	-

Table of Contents

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- - -	- - -	275 195 32	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{thJA}=50 °C/W[2]
Pulsed drain current[3]	$I_{D,pulse}$	-	-	1100	A	T_C=25 °C
Avalanche energy, single pulse[4]	E_{AS}	-	-	580	mJ	I_D=50 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	217 3.0	W	T_C=25 °C T_A=25 °C, R_{thJA}=50 °C/W[2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	R_{thJC}	-	-	0.7	°C/W	-
Thermal resistance, junction - case, top	R_{thJC}	-	-	20	°C/W	-
Thermal resistance, junction - ambient, 6 cm² cooling area[2]	R_{thJA}	-	-	50	°C/W	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[3] See Diagrams 3 and 4 for more detailed information
[4] See Diagram 14 for more detailed information

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	60	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.25	3.0	3.45	V	V_{DS}=V_{GS}, I_D=120 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1 100	µA	V_{DS}=60 V, V_{GS}=0 V, T_j=25 °C V_{DS}=60 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	1.3	1.55	mΩ	V_{GS}=10 V, I_D=50 A
Gate resistance	R_G	-	2.0	2.6	Ω	-
Transconductance[1]	g_{fs}	28	56	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=50 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance[1]	C_{iss}	-	6900	9000	pF	V_{GS}=0 V, V_{DS}=30 V, f=1 MHz
Output capacitance[1]	C_{oss}	-	1300	1700	pF	V_{GS}=0 V, V_{DS}=30 V, f=1 MHz
Reverse transfer capacitance[1]	C_{rss}	-	55	96	pF	V_{GS}=0 V, V_{DS}=30 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	17	-	ns	V_{DD}=30 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	16	-	ns	V_{DD}=30 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	31	-	ns	V_{DD}=30 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Fall time	t_f	-	15	-	ns	V_{DD}=30 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω

Table 6 Gate charge characteristics[2]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	41	-	nC	V_{DD}=30 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	21	-	nC	V_{DD}=30 V, I_D=50 A, V_{GS}=0 to 10 V
Gate to drain charge[1]	Q_{gd}	-	16	24	nC	V_{DD}=30 V, I_D=50 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	36	-	nC	V_{DD}=30 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge total[1]	Q_g	-	90	113	nC	V_{DD}=30 V, I_D=50 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	5.9	-	V	V_{DD}=30 V, I_D=50 A, V_{GS}=0 to 10 V
Output charge[1]	Q_{oss}	-	91	121	nC	V_{DS}=30 V, V_{GS}=0 V

[1] Defined by design. Not subject to production test.
[2] See ″Gate charge waveforms″ for parameter definition

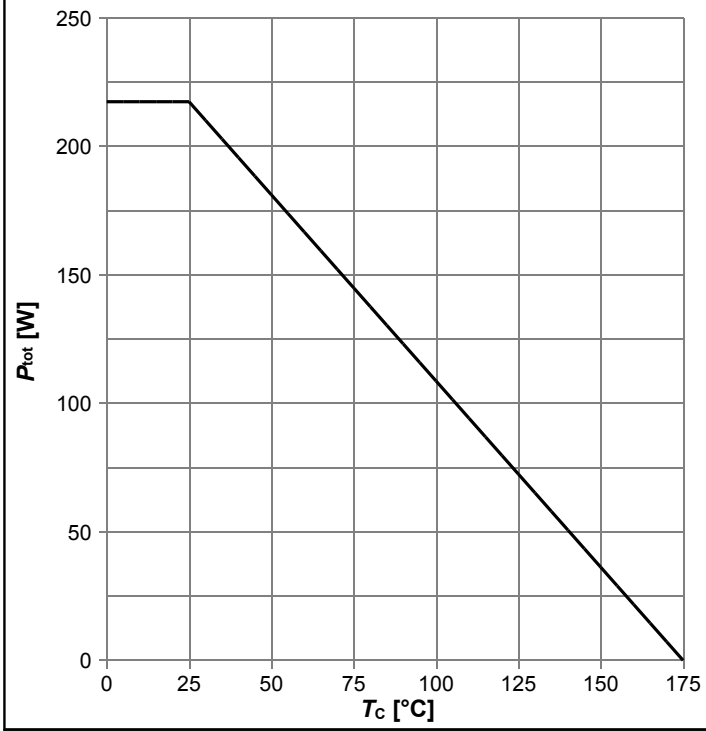
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	163	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	1100	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.82	1.2	V	V_{GS}=0 V, I_F=50 A, T_j=25 °C
Reverse recovery time[1)]	t_{rr}	-	39	78	ns	V_R=30 V, I_F=50 A, di_F/dt=100 A/µs
Reverse recovery charge[1)]	Q_{rr}	-	42	84	nC	V_R=30 V, I_F=50 A, di_F/dt=100 A/µs

[1)] Defined by design. Not subject to production test.

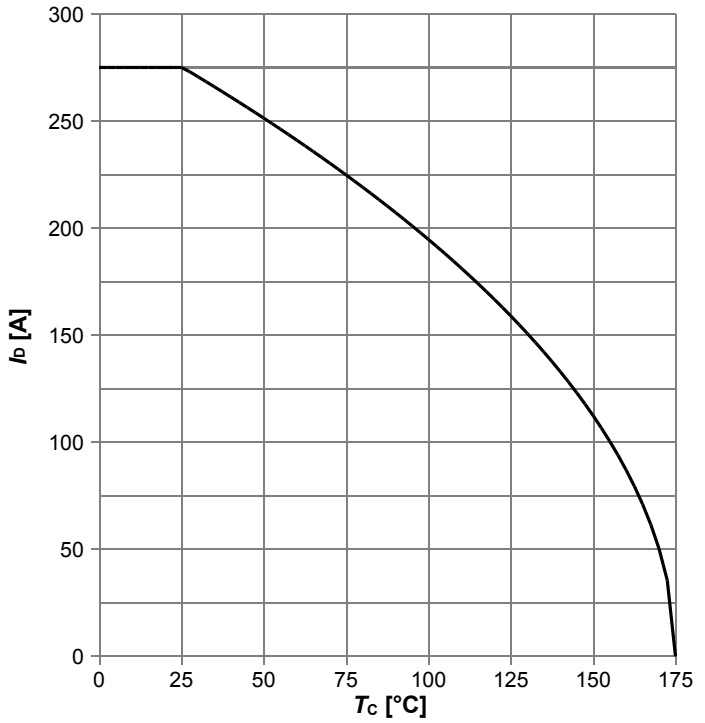
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



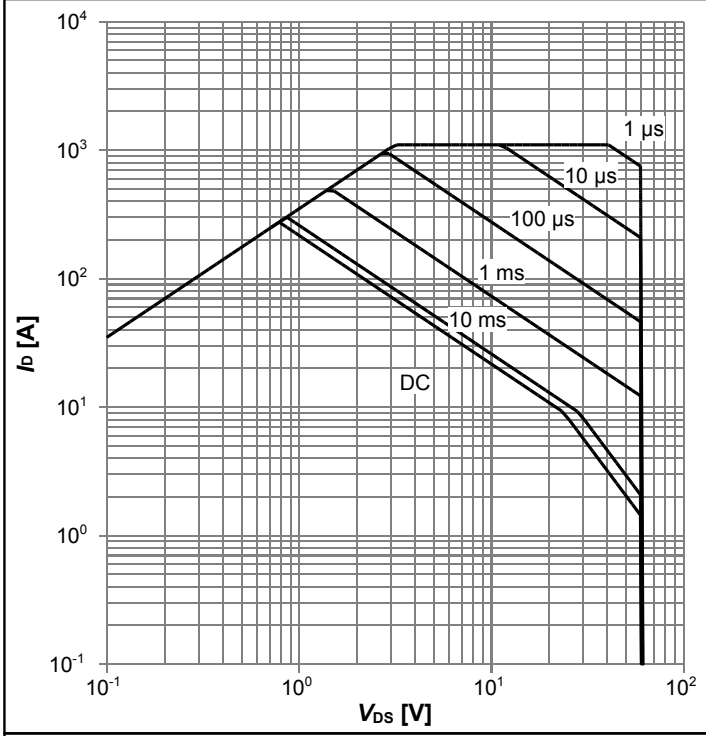
$P_{tot}=f(T_C)$

Diagram 2: Drain current



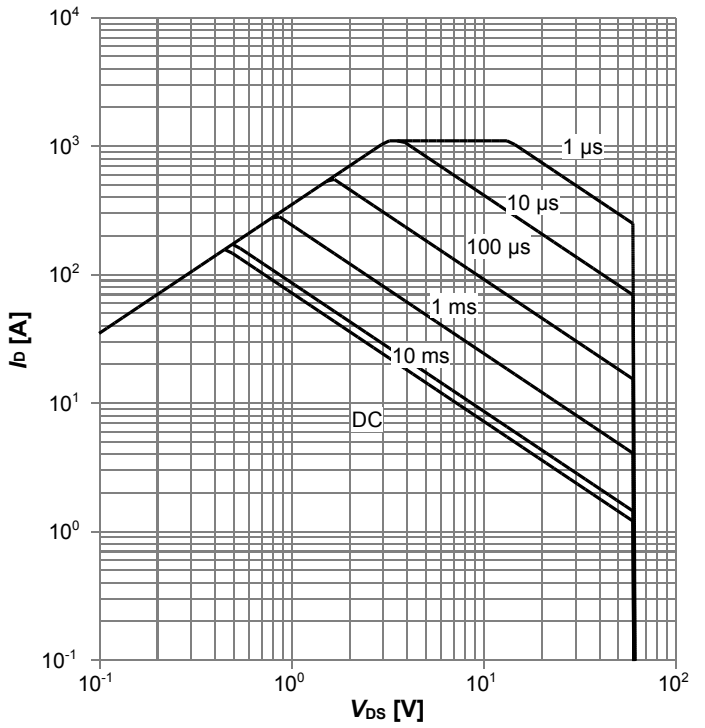
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



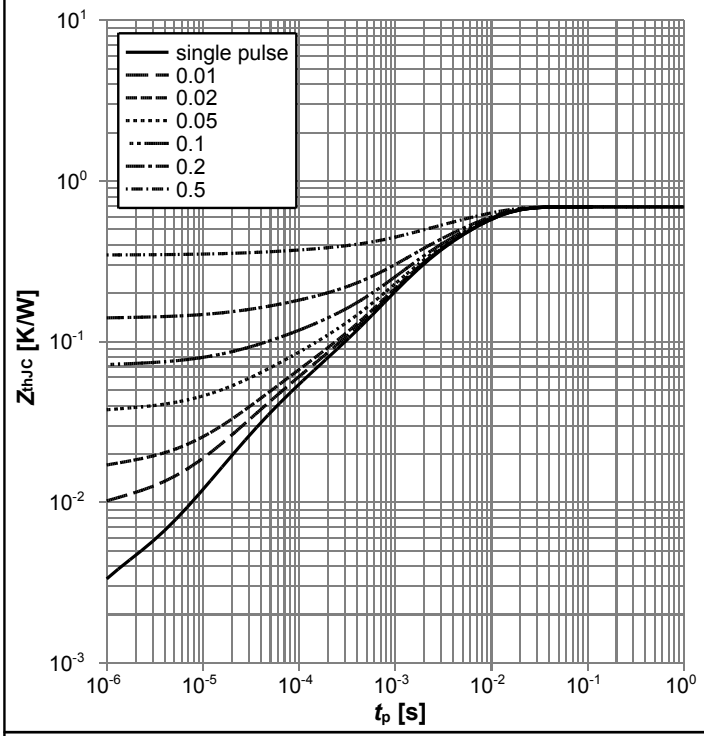
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Safe operating area



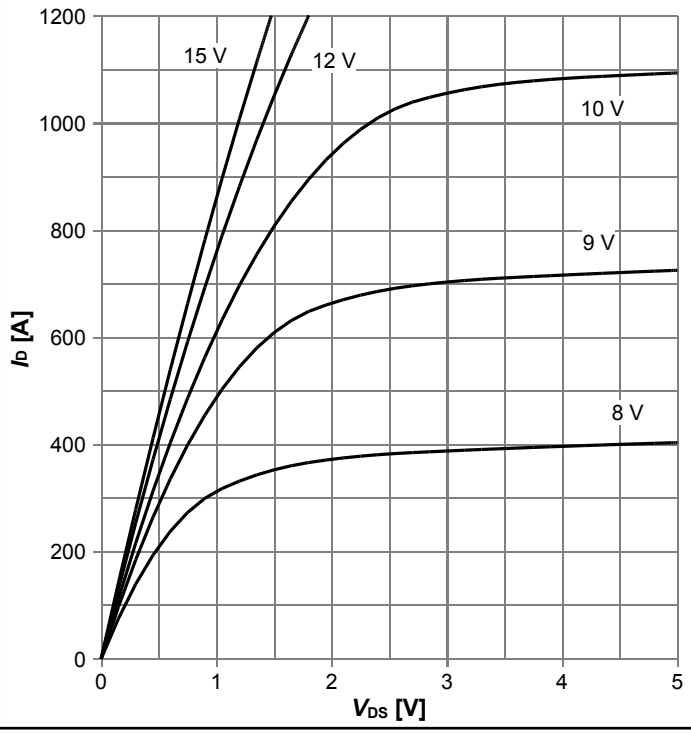
$I_D=f(V_{DS})$; $T_C=125$ °C; $D=0$; parameter: t_p

Diagram 5: Max. transient thermal impedance



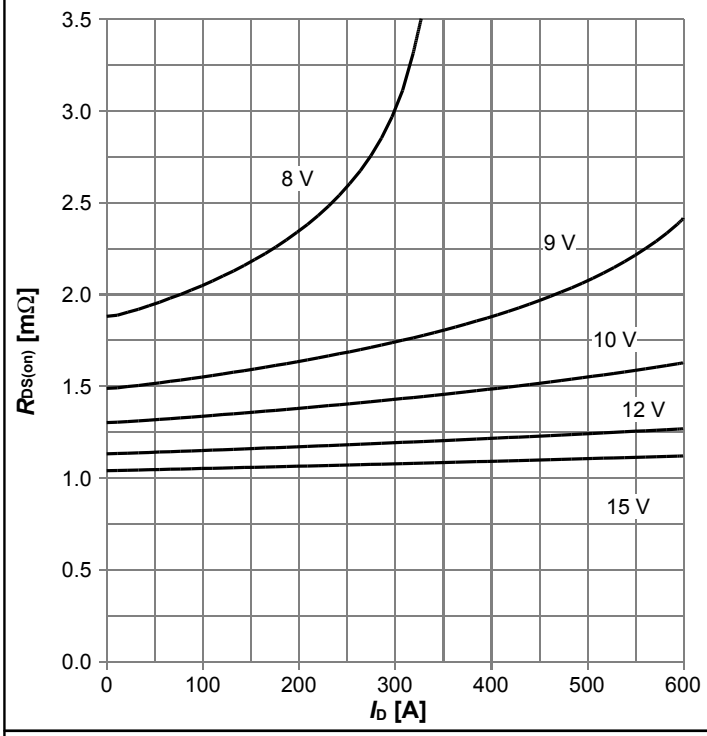
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 6: Typ. output characteristics



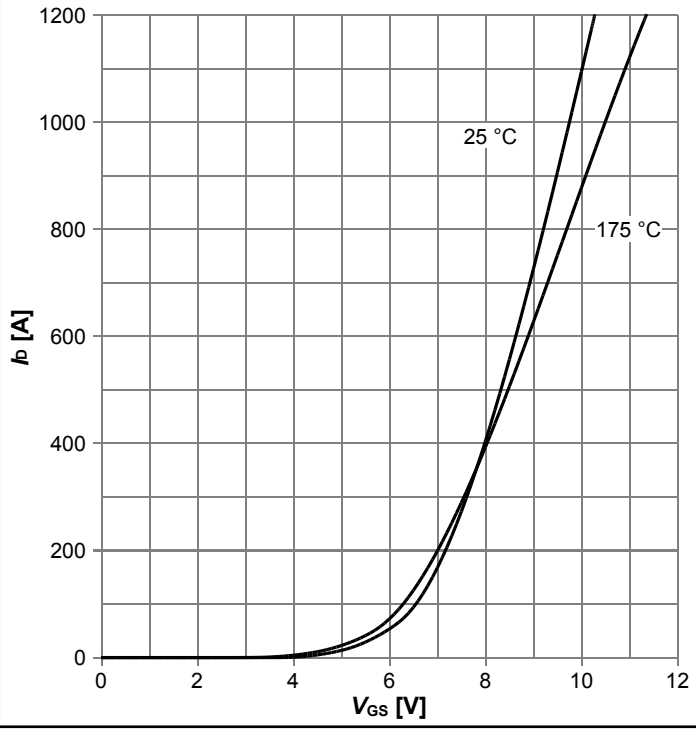
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. drain-source on resistance



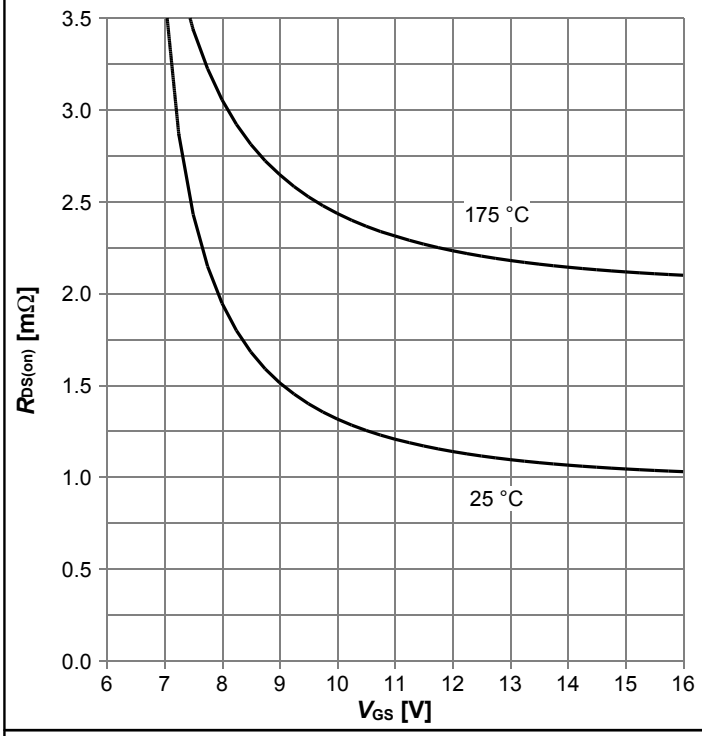
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 8: Typ. transfer characteristics



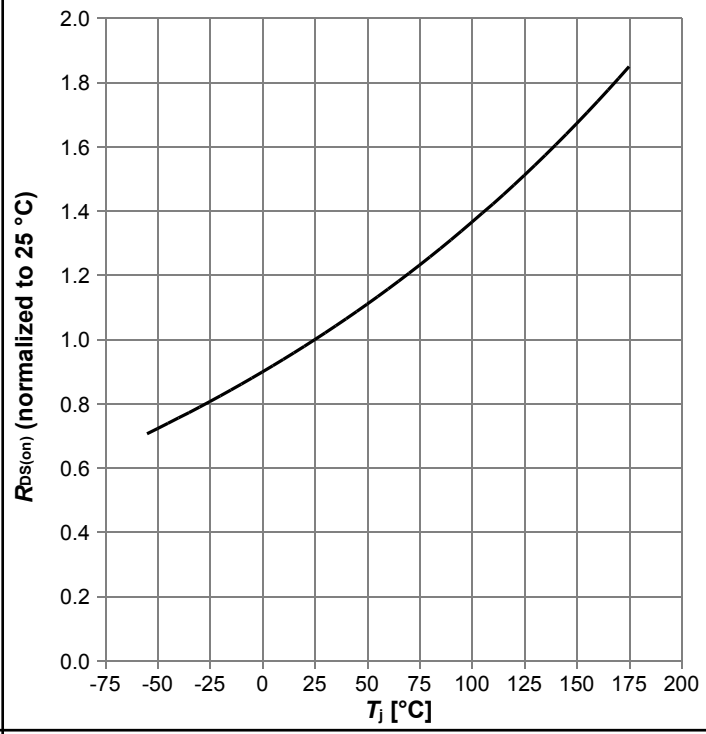
I_D=f(V_{GS}), |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

Diagram 9: Typ. drain-source on resistance



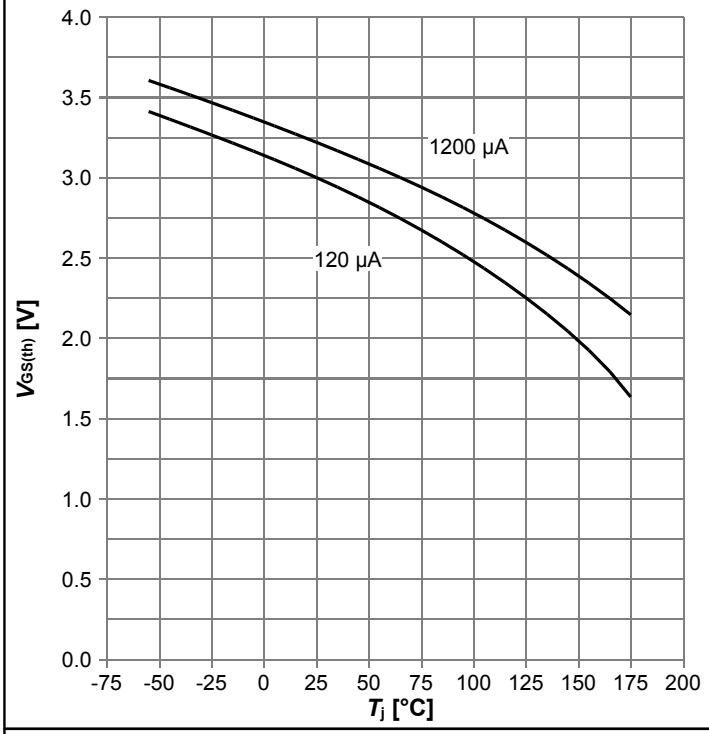
$R_{DS(on)}$=f(V_{GS}), I_D=50 A; parameter: T_j

Diagram 10: Normalized drain-source on resistance



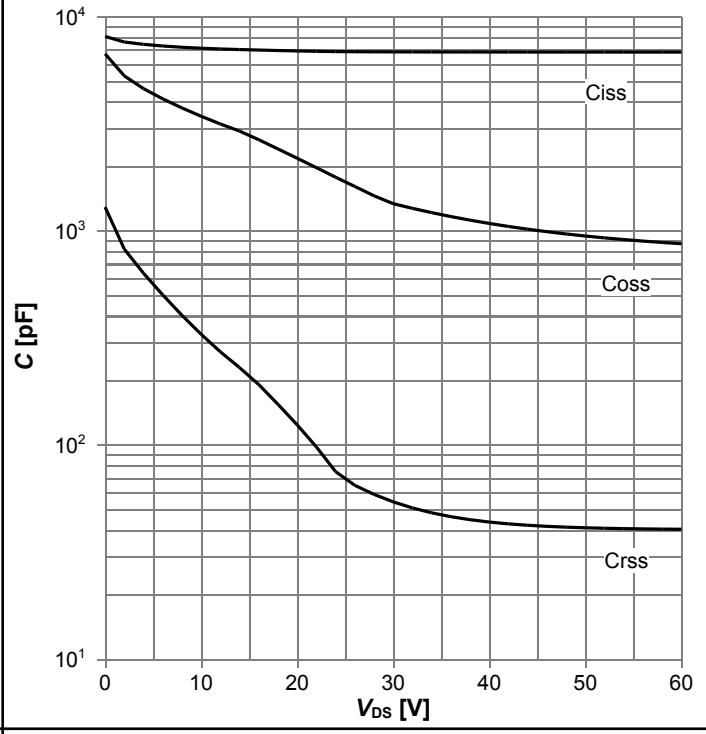
$R_{DS(on)}$=f(T_j), I_D=50 A, V_{GS}=10 V

Diagram 11: Typ. gate threshold voltage



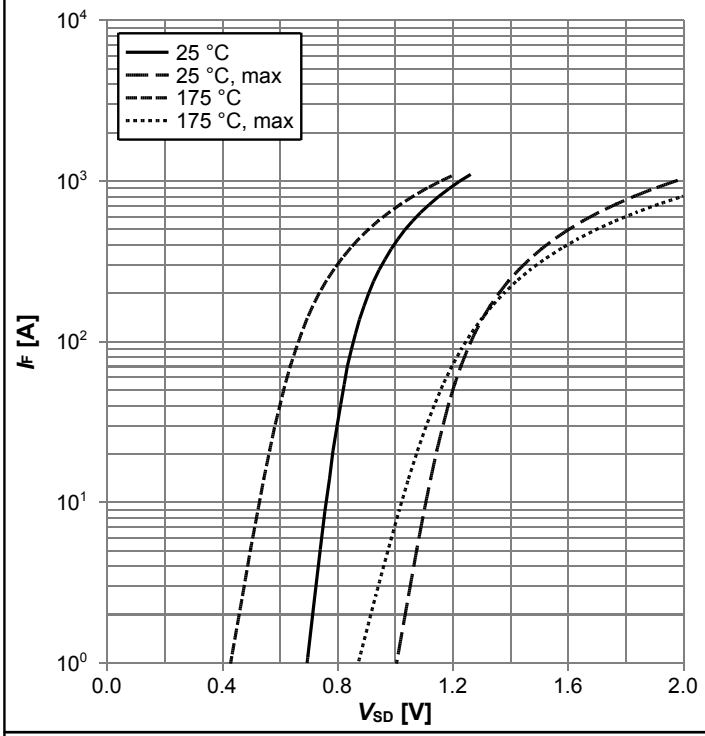
$V_{GS(th)}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 12: Typ. capacitances



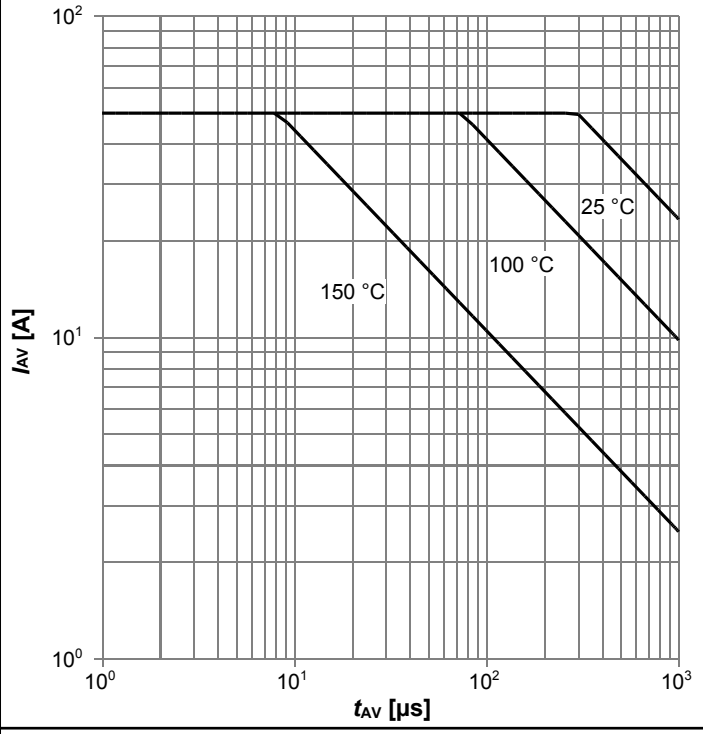
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 13: Forward characteristics of reverse diode



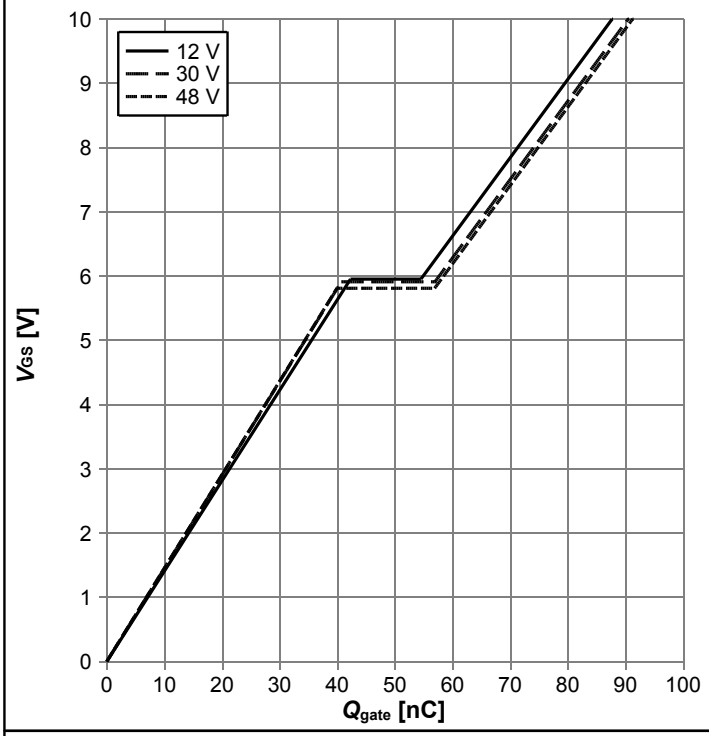
$I_F=f(V_{SD})$; parameter: T_j

Diagram 14: Avalanche characteristics



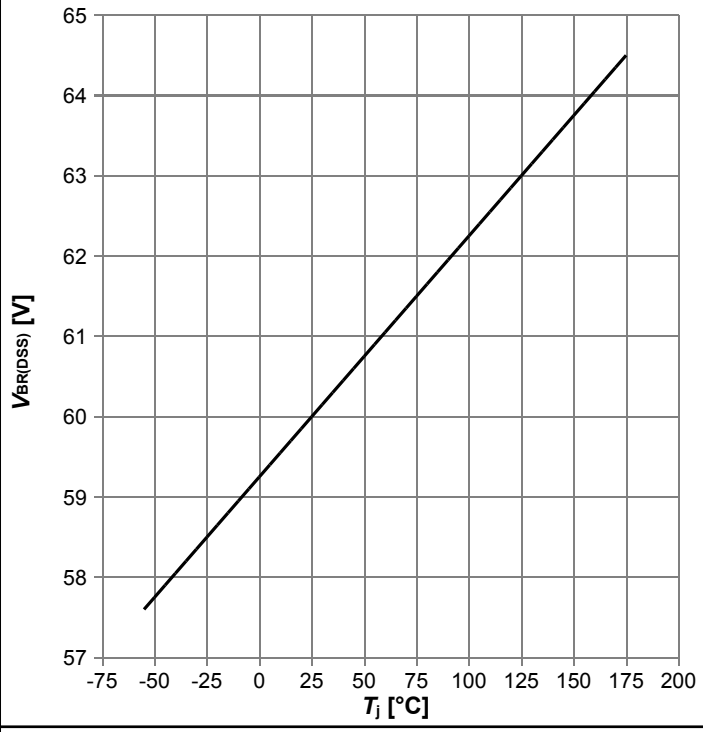
$I_{AS}=f(t_{AV})$; R_{GS}=25 Ω; parameter: $T_{j,start}$

Diagram 15: Typ. gate charge



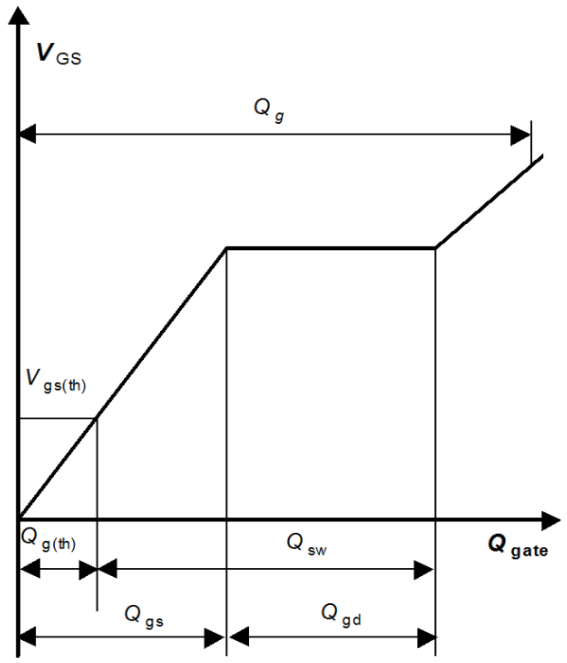
$V_{GS}=f(Q_{gate})$, I_D=50 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 16: Drain-source breakdown voltage

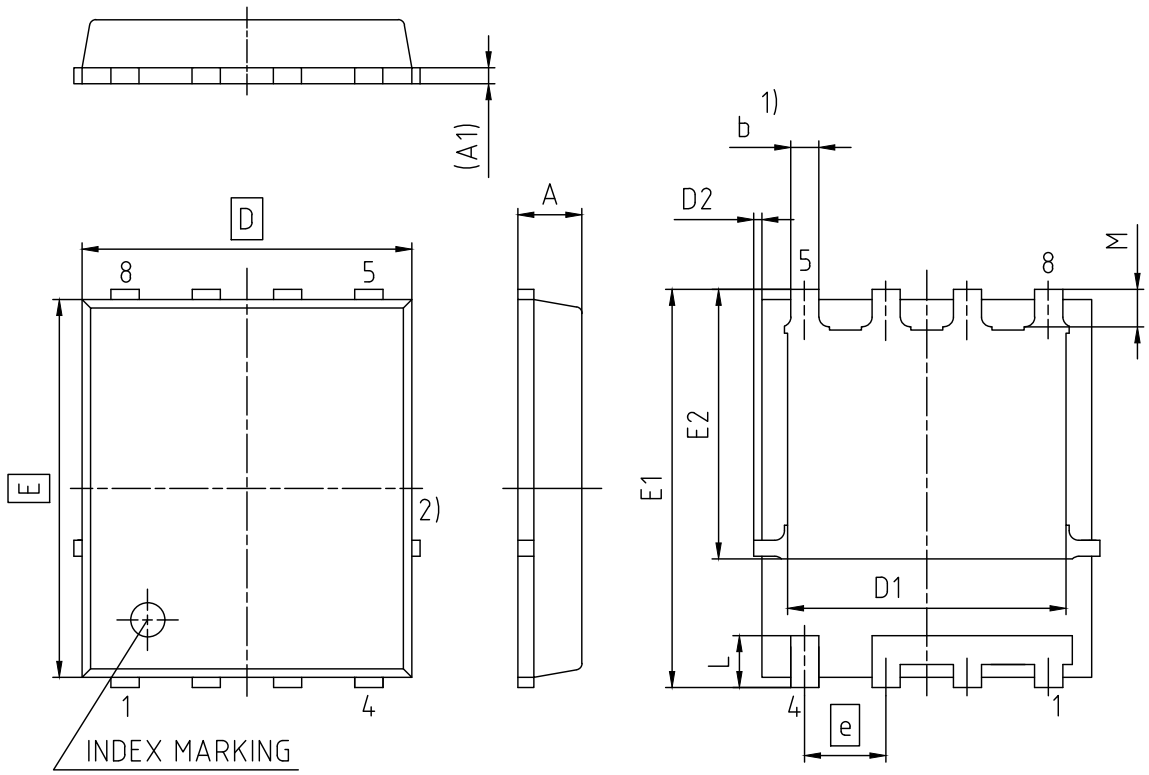


$V_{BR(DSS)}=f(T_j)$; I_D=1 mA

Diagram Gate charge waveforms



5 Package Outlines



1) EXCLUDING MOLD FLASH
2) REMOVAL ON MOLD GATE
INTRUSION 0.1 MM
PROTRUSION 0.1 MM
LEAD LENGTH UP TO ANTI FLASH LINE
ALL METAL SURFACES ARE PLATED, EXCEPT AREA OF CUT

DIMENSION	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.20
A1	0.15	0.35
b	0.26	0.54
D	4.80	5.35
D1	3.70	4.40
D2	0.00	0.23
E	5.70	6.10
E1	5.90	6.42
E2	3.88	4.42
e	1.27	
L	0.69	0.90
M	0.45	0.69

DOCUMENT NO. Z8B000193699
REVISION 04
SCALE 10:1 0 1 2 3mm
EUROPEAN PROJECTION
ISSUE DATE 05.11.2019

Figure 1 Outline PG-TDSON-8 FL, dimensions in mm

Revision History

ISC015N06NM5LF2

Revision: 2023-11-08, Rev. 2.1

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2023-11-08	Update sales name and marking

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